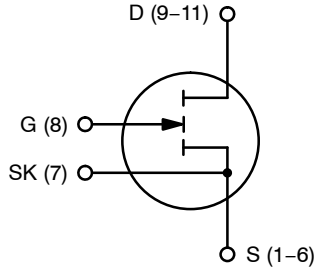
Enhancement Mode Gallium Nitride (GaN) HEMT

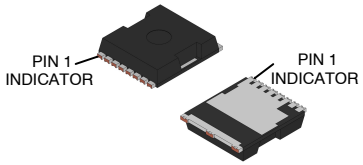
650 V, 39 mΩ, 40 A, PDSO-F9

Preliminary Document

NTBL050N65GN1

$V_{(BR)DSS}$	$R_{DS(ON)}$ TYP	I_{DS} MAX
650 V	39 mΩ	40 A





PDSO-F9 10.38 x 9.90 x 2.30, 1.20P
CASE 207AA

Features

- Low $R_{DS(ON)}$ to Minimize Conduction Losses
- Ultra Low Gate Charge for High Speed Switching
- FOM-Q_G = 367 nC*mΩ
- Small Footprint for High Density PCB Design
- Pb-Free, Halogen Free and RoHS Compliant

Typical Applications

- High Density Power Modules
- High Frequency AC-DC and DC-DC Converters
- High Performance PSU for Datacenter and Industrial
- Resonant Conversion

MAXIMUM RATINGS (T_J = 25 °C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	650	V
Drain-to-Source Transient Voltage, t_P < 200 μs	$V_{DS(TRAN)}$	800	V
Gate-to-Source Voltage	V_{GS}	−6 to 7	V
Gate-to-Source Transient Voltage, t_P = 50 ns, f_P = 100 kHz, open drain	$V_{GS(PULSE)}$	−20 to 10	V
Continuous Drain Current, T_{CASE} = 25 °C T_{CASE} = 100 °C	I_{DS}	 40 30	A
Pulsed Drain Current, t_P < 10 μs, T_J = 25 °C T_J = 125 °C	$I_{DS(PULSE)}$	 77 40	A
Power Dissipation, V_{GS} = 6 V, T_{CASE} = 25 °C	P_{TOT}	250	W
Operating Junction Temperature	T_J	−55 to 150	°C
Storage Temperature	T_{STG}	−55 to 150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

MARKING DIAGRAM

BL050N65GN1	= Specific Device Code
A	= Assembly Site
Y	= Year of Production
WW	= Work Week Number
ZZZ	= Assembly Lot Number

ORDERING INFORMATION

See detailed ordering and shipping information on page 3 of this data sheet.

This Preliminary document is for informational purposes only. **onsemi** may update or withdraw it without notice. Content and referenced products are under development and subject to change.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Junction-to-Case	$R_{\theta JC}$	0.5	°C/W
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	56	°C/W
Maximum Soldering Temperature (MSL3)	T_{SLD}	260	°C

1. Device on 1 in^2, 2 oz copper pad on single layer FR-4 PCB

ELECTRICAL CHARACTERISTICS (T_J = 25 °C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V	650			V
Drain-to-Source Leakage Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = 650 V		8	TBD	μA
		V_{GS} = 0 V, V_{DS} = 650 V, T_J = 125 °C		20		
Gate-to-Source Leakage Current	I_{GSS}	V_{GS} = 6 V, V_{DS} = 0 V		250	TBD	μA
		V_{GS} = 6 V, V_{DS} = 0 V, T_J = 125 °C		TBD		μA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	$R_{DS(ON)}$	V_{GS} = 6 V, I_{DS} = 18 A		39	50	mΩ
		V_{GS} = 6 V, I_{DS} = 18 A, T_J = 125 °C		75		
Gate Threshold Voltage	$V_{GS(TH)}$	V_{DS} = V_{GS}, I_{DS} = 50 mA, T_J = 25 °C		1.7		V
		V_{DS} = V_{GS}, I_{DS} = 50 mA, T_J = 125 °C		1.6		
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{ISS}	V_{DS} = 400 V, V_{GS} = 0 V, f = 1 MHz		342		pF
Output Capacitance	C_{OSS}			125		
Reverse Transfer Capacitance	C_{RSS}			1.5		
Output Capacitance, Energy Related	$C_{OSS(ER)}$	V_{DS} = 0 V to 400 V, V_{GS} = 0 V		189		pF
Output Capacitance, Time Related	$C_{OSS(TR)}$			269		
Output Charge	Q_{OSS}			107		nC
Output Capacitance Stored Energy	E_{OSS}			15		μJ
Gate Resistance	R_G	f = 5 MHz		1.5		Ω
Gate Charge	Q_G	V_{DS} = 400 V, I_{DS} = 18 A, V_{GS} = 0/6 V		9.4		nC
Gate-to-Source Charge	Q_{GS}			0.9		
Gate-to-Drain Charge	Q_{GD}			4.0		
Gate Plateau Voltage	V_{PLAT}			2.5		V
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_{D(ON)}$	V_{DS} = 400 V, I_{DS} = 18 A, V_{GS} = 0/6 V, $R_{G,ON}$ = 10 Ω, $R_{G,OFF}$ = 2.2 Ω		9.6		ns
Turn-Off Delay Time	$t_{D(OFF)}$			10.5		ns
Turn-On Rise Time	t_R			13.3		ns
Turn-Off Fall Time	t_F			9		ns
REVERSE CONDUCTION CHARACTERISTICS						
Source-to-Drain Reverse Voltage	V_{SD}	V_{GS} = −2 V, I_{SD} = 18 A		4.9		V
		V_{GS} = 0 V, I_{SD} = 18 A		2.9		
		V_{GS} = 6 V, I_{SD} = 18 A		0.7		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Gate Drive Guidelines

This GaN device utilizes a Schottky gate structure, which behaves similarly to a MOSFET with a purely capacitive input and does not require continuous gate current during the on-state. For optimal performance, apply a low-impedance gate driver with appropriate gate resistance to control switching speed and limit ringing. A typical gate voltage of **6 V** is recommended, with optional negative gate bias for hard-switching applications to improve dv/dt immunity and prevent false turn-on. Minimize gate loop inductance (<1 nH) through careful PCB layout and short connections. For additional robustness, Zener clamps may be used to limit gate voltage in both polarities.

ORDERING INFORMATION

Device Order Number	Package Type	Shipping†
ENGNTBL050N65GN1TXG	PDSO-F9 10.38 x 9.90 x 2.30, 1.20P	1200 / Tape & Reel

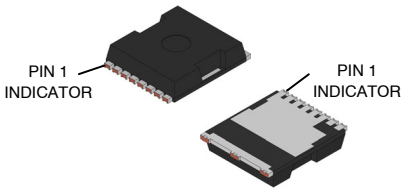
† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

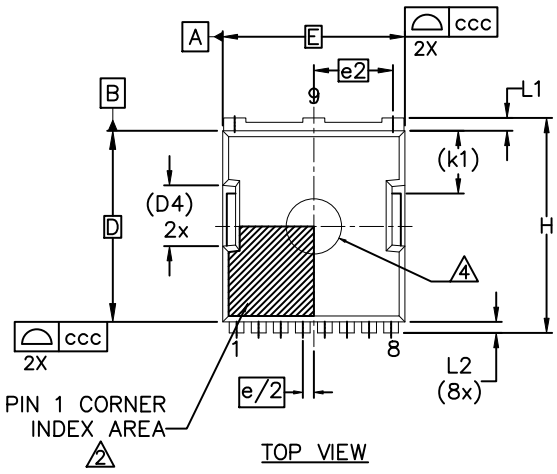
REVISION HISTORY

Revision	Description of Changes	Date
P0	Initial Preliminary Document release.	5/4/2026
P1	Updated case outline and package information; added the marking diagram, added shipping information to the Ordering Information table.	7/3/2026

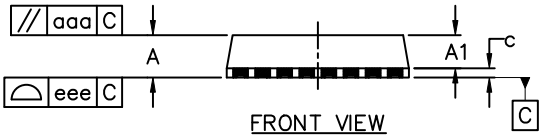
PDSO-F9 10.38x9.90x2.30, 1.20P
CASE 207AA
ISSUE O

DATE 25 FEB 2026

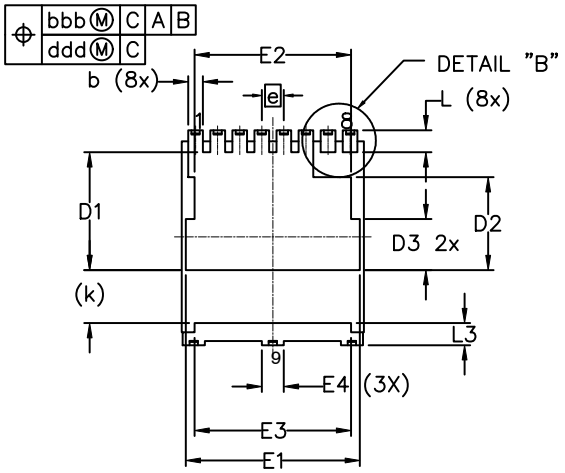




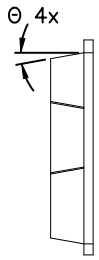
TOP VIEW



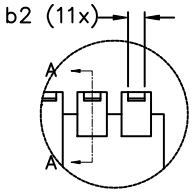
FRONT VIEW



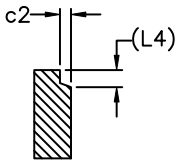
BOTTOM VIEW



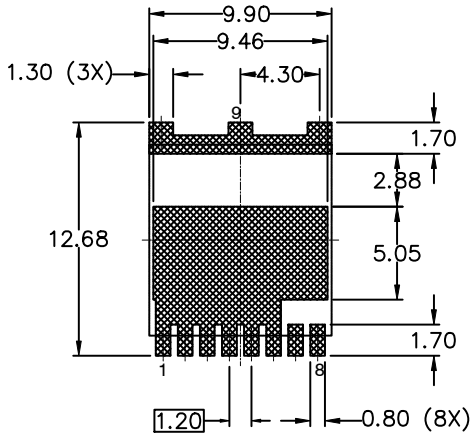
SIDE VIEW



DETAIL "B"
SCALE: 2X



SECTION "A–A"
SCALE: 4X

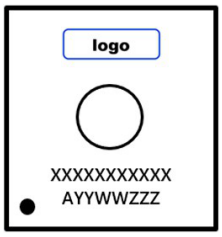


LAND PATTERN
RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB–FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	2.15	2.30	2.45
A1	1.65	1.80	1.95
b	0.70	0.80	0.90
b2	0.31	0.43	0.55
c	0.40	0.50	0.60
c2	0.10	–	–
D	10.38 BSC		
D1	6.20	6.40	6.60
D2	4.85	5.05	5.25
D3	2.57	2.77	3.97
D4	3.30 REF		
E	9.90 BSC		
E1	9.26	9.46	9.66
E2	8.30	8.50	8.70
E3	8.30	8.50	8.70
E4	1.10	1.20	1.30
e	1.20 BSC		
e/2	0.60 BSC		
e2	4.30 BSC		
H	11.48	11.68	11.88
L	1.00	1.20	1.40
L1	0.50	0.70	0.90
L2	0.50	0.60	0.70
L3	1.00	1.20	1.40
L4	0.23 REF		
k	2.88 REF		
k1	3.41 REF		
Θ	10° REF		
aaa	0.20		
bbb	0.25		
ccc	0.20		
ddd	0.20		
eee	0.20		

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
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*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE HATCHED AREA.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH AND BURR.
4. THE LOCATION AND SIZE OF EJECTOR MARKS ARE OPTIONAL.

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DESCRIPTION:	**PDSO-F9 10.38x9.90x2.30, 1.20P**		**PAGE 1 OF 1**

ADDITIONAL INFORMATION

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